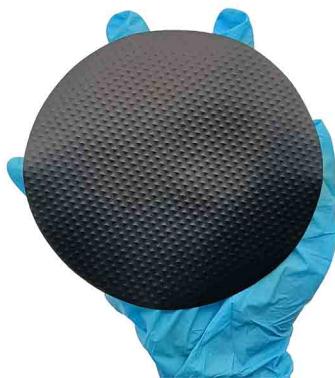


ESD Wafer Film

◆ Product Description

ESD wafer film is a functional film material used in the semiconductor industry to protect wafers from electrostatic damage and physical damage during production, transportation, storage and processing. Its core value lies in electrostatic protection and clean surface protection of wafers, making it an indispensable key auxiliary material in the semiconductor industry chain.



- Precise and Controllable Antistatic Performance
- High Cleanliness and Low Extractable Content Characteristics
- Excellent Physical Protection Capability
- Strong Process Compatibility
- Stable Environmental Adaptability

◆ Product Structure

- The ESD wafer film adopts a multi-layer composite structure design, whose core is composed of PE base material layer, antistatic layer and functional adaptation layer. The overall structural design is centered on electrostatic protection, physical protection and process adaptation, so as to meet the full-process protection requirements of wafer production, processing, warehousing and transportation.

◆ Typical Product Data and Physical Properties

Material: PE (Polyethylene)
Adhesive Layer: Acrylic Pressure-sensitive Adhesive
Texture: Diamond Pattern
Thickness: 0.1 MM
Diameter: 127 MM
Antistatic Resistance Value: $\leq 10E9\Omega$
Tensile Strength: ≥ 20 MPa
Elongation at Break: $\geq 150\%$
Peel Force: 0.1~1.0 N/25 MM
Packaging Specification: Packaged in shielding bags

Availability:

Item#	Diameter	Packaging	Weight
1.2.13.09.0056	127MM	200pcs/bag	0.32kg

◆ Technical and Application Assistance

HORB provides a technical hotline to answer your technical and application related questions.

◆ Note:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. HORB data for reference only

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